

AMENDMENT(S) TO THE SPECIFICATION

Please replace the paragraph beginning at page 6, line 6, with the following rewritten paragraph:

The method includes the steps of: forming a first insulating layer 2 of a photoresist material on the pad-mounting surface 10 (see Fig. 1); forming a plurality of first and second holes 13 in the first insulating layer 2 through etching techniques (only one of the first and second holes 13 is shown in Fig. 2), each of the first and second holes 13 exposing a respective one of the first and second bonding pads 11, 12 from the first insulating layer 2; forming a plurality of first metal layers 41 on the first bonding pads 11, respectively, through plating techniques; forming a plurality of first level conductive horizontal bodies 3 (see Figs. 3 and 4), each of which has an end section 31 that fills a respective one of the first holes 13 to electrically connect with a respective one of the first bonding pads 11 through a respective first metal layer 41, and an extension 32 that extends from the end section 31, that is formed on the first insulating layer 2, and that has a connecting end 320 horizontally offset from the respective one of the first holes 13, each of the first level conductive horizontal bodies 3 including a conductive paste layer 42 that has a first portion extending from the first metal layer 41, and a second portion formed on the first insulating layer 2, and a second metal layer 43 formed on and cooperating with the second portion of the conductive paste layer 42 to define the extension 32 of the respective one of the first level conductive horizontal bodies 3, the connecting end 320 of the extension 32 of each of the first level conductive horizontal bodies 3 being flattened, the second metal layer ~~[[42]]~~ 43 preferably including a nickel sub-layer and a gold sub-layer (not shown); forming a plurality of first level conductive vertical bodies 3', each of which fills a respective one of the second holes 13 in the first insulating layer 2 to electrically connect with a respective one of the second bonding pads 12 (see Figs. 3 and 4), and each of which has a connecting end 31' that extends through the respective one of the second holes 13 in the first insulating layer 2; forming a second insulating layer 5 of the photoresist material on the first insulating layer 2 (see Fig. 5); forming a plurality of first and second holes 50 in the second insulating layer 5 (see Fig. 5), each of the first holes 50 in the second insulating layer 5 exposing the connecting end 320 of the extension 32 of a respective one of the first level conductive horizontal bodies 3, each of the

second holes 50 in the second insulating layer 5 exposing the connecting end 31' of a respective one of the first level conductive vertical bodies 3'; forming a plurality of second level conductive vertical bodies 6 (see Fig. 6), each of which is electrically connected to the connecting end 320 of the extension 32 of a respective one of the first level conductive horizontal bodies 3, each of which fills a respective one of the first holes 50 in the second insulating layer 5, and each of which has a connecting end 60 that extends through and that is vertically aligned with the respective one of the first holes 50 in the second insulating layer 5; forming a plurality of second level conductive horizontal bodies 6' (see Fig. 6), each of which has an end section 60' that fills a respective one of the second holes 50 in the second insulating layer 5 to electrically connect with the connecting end 31' of a respective one of the first level conductive vertical bodies 3', and an extension 61' that extends from the end section 60' of a respective one of the second level conductive horizontal bodies 6', that is formed on the second insulating layer 5, and that has a connecting end 611' horizontally offset from the respective one of the second holes 50 in the second insulating layer 5, the connecting end 611' of the extension 61' of each of the second level conductive horizontal bodies 6' being flattened; forming a third insulating layer 7 of the photoresist material on the second insulating layer 5 (see Fig. 7); forming a plurality of first and second holes 70 in the third insulating layer 7 (see Fig. 7) such that the connecting end 60 of each of the second level conductive vertical bodies 6 and the connecting end 611' of the extension 61' of each of the second level conductive horizontal bodies 6' extend into a respective one of the first and second holes 70 in the third insulating layer 7; forming a third metal layer 8 on the connecting end 60 of each of the second level conductive vertical bodies 6 and on the connecting end 611' of the extension 61' of each of the second level conductive horizontal bodies 6' (see Fig. 7); and forming a plurality of first and second conductive bumps 9, 9' (see Fig. 8) such that each of the first conductive bumps 9 extends into a respective one of the first holes 70 in the third insulating layer 7 to electrically connect with the connecting end 60 of a respective one of the second level conductive vertical bodies 6 through the third metal layer 8, and that each of the second conductive bumps 9' extends into a respective one of the second holes 70 in the third insulating layer 7 to electrically connect with the connecting end 611' of the extension 61 of a respective one of the second level conductive horizontal bodies 6' through the third metal layer 8.

Note that the multi-level interconnect structure is not limited to the above preferred embodiment, and can include more levels of the insulating layers and the conductive horizontal and vertical bodies.